

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	Customer Number: 89518
	:	
LIN, Mou-Shiung	:	Confirmation Number: 8665
	:	
Application No.: 10/755,042	:	Group Art Unit: 2815
	:	
Filed: January 9, 2004	:	Examiner: JACKSON JR., Jerome
	:	
For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME	:	

RESPONSE/AMENDMENT

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF ELECTRONIC TRANSMISSION
I hereby certify that this correspondence is being electronically-transmitted to the
United States Patent and Trademark Office on June 27, 2011
/lynnec.j.craig/

Lynne J. Craig

Sir:

It is respectfully requested that the time for response to the final Office Action dated February 25, 2011 be extended for one month to Monday, June 27, 2011. Please charge the extension fee of \$130.00 to Deposit Account No. 502624. Please charge any additional fees or credit any overpayment to Deposit Account No. 502624.

In response to the final Office Action dated February 25, 2011, a Request For Continued Examination being filed herewith, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.

An **Appendix** is attached after the last page, which shows the status of related cases.